



Black Opal HX100 DDR5 Memory



One-Click
Overclocking



PMIC



Premium
DRAM ICs



Optimized Heat
Dissipation

Biwin HX100 DDR5 High-Performance Memory with great overclocking potential stands out with its exceptional design aesthetics and strong performance. HX100 has won the “Oscars” of the design world – the German Red Dot Award. Combining design excellence, efficient heat dissipation, advanced PMIC and high-quality ICs HX100 is compatible with major platforms. The HX100 modules are perfect for overclocking enthusiasts, PC builders and competitive gamers, ensuring top-tier performance in intense scenarios.

► Product Features

Premium Heat Dissipation, Stable Overclocking

The special design of Biwin HX100 features a high-efficient thermal conductive silicone pad and the highest-grade aluminum heat spreader with parallel cooling fins, forming an armor that combines aesthetics with cooling efficiency.

PMIC, Unlocked Voltage

Equipped with an unlocked PMIC for better overclocking, Biwin HX100 offers a continuous and stable power delivery, satisfying your exploration of memory overclocking.

DDR5 Overclocking, Superior Gaming Performance

With gaming-grade performance, high frequency, and low latency, HX100 is designed for gamers and overclocking enthusiasts, supporting intense competitions.

Supporting Intel XMP 3.0 and AMD E.X.P.O

Biwin HX100 supports overclocking with XMP 3.0 and AMD EXPO to unlock high-speed with one click, and to help you outpace your gaming competitors right from the start.

► Biwin Storage Black Opal Series

For decades, Biwin has made the critical storage and memory in many of the leading digital devices that have defined our digital world. The Biwin consumer brand offers the best of Biwin's experience, a range of SSDs, DRAM, memory cards and related accessories that will help you get the most out of your devices.

Biwin Black Opal is especially designed for gamers, enthusiasts, modders and overclockers seeking top-tier performance. It is the result of years of experience in SSDs and DRAM manufacturing. The quality is top tier and results from a fusion of technological experiences. The durability matches the more strenuous needs of gamers, content providers and professional users.

► Specifications

Model Name	Biwin Black Opal HX100
RAM Type	DDR5
Color	Black / White
Capacity	32 GB: 16 GB x 2 48 GB: 24 GB x 2 64 GB: 32 GB x 2
Data Rate	6000 / 6400 / 6600 / 6800 / 7200 MT/s
Timing	CL30 / CL32 / CL34 / CL36
Rank	1R x 8 / 2R x 8
Operating Voltage	1.35 V / 1.4 V
Pin	288 Pin
Dimensions	136.60 x 47.00 x 8.40 mm
Operating Temperature	0°C to +85°C
Storage Temperature	-40°C to +85°C
Certifications	CE, FCC, RoHS, VCCI, RCM, BSMI, UKCA
Warranty	Limited Lifetime*

► Order Information

Part Number	Capacity	Rank	Data Rate	Timing	Voltage	Package	Color	Intel XMP 3.0 & AMD EXPO Support
B5HX100326030ER2G-BB001	32 GB	1R *8	6000 MT/s	CL30-38-38-76	1.35 V	16 GB x 2 pcs	Black	XMP 3.0 & E.X.P.O
B5HX100326436ER2G-BB009	32 GB	1R *8	6400 MT/s	CL36-48-48-102	1.35 V	16 GB x 2 pcs	Black	XMP 3.0
B5HX100326436ER2G-BS009	32 GB	1R *8	6400 MT/s	CL36-48-48-102	1.35 V	16 GB x 2 pcs	Silver	XMP 3.0
B5HX100326432FR2G-BB002	32 GB	1R *8	6400 MT/s	CL32-39-39-102	1.4 V	16 GB x 2 pcs	Black	XMP 3.0 & E.X.P.O
B5HX100326634FR2G-BB004	32 GB	1R *8	6600 MT/s	CL34-40-40-105	1.4 V	16 GB x 2 pcs	Black	XMP 3.0
B5HX100326834FR2G-BB003	32 GB	1R *8	6800 MT/s	CL34-45-45-108	1.4 V	16 GB x 2 pcs	Black	XMP 3.0 & E.X.P.O
B5HX100327234FR2G-BB005	32 GB	1R *8	7200 MT/s	CL34-45-45-115	1.4 V	16 GB x 2 pcs	Black	XMP 3.0

B5HX100326030ER2G-BS001	32 GB	1R *8	6000 MT/s	CL30-38-38-76	1.35 V	16 GB x 2 pcs	Silver	XMP 3.0 & E.X.P.O
B5HX100326432FR2G-BS002	32 GB	1R *8	6400 MT/s	CL32-39-39-102	1.4 V	16 GB x 2 pcs	Silver	XMP 3.0 & E.X.P.O
B5HX100326634FR2G-BS004	32 GB	1R *8	6600 MT/s	CL34-40-40-105	1.4 V	16 GB x 2 pcs	Silver	XMP 3.0
B5HX100326834FR2G-BS003	32 GB	1R *8	6800 MT/s	CL34-45-45-108	1.4 V	16 GB x 2 pcs	Silver	XMP 3.0 & E.X.P.O
B5HX100327234FR2G-BS005	32 GB	1R *8	7200 MT/s	CL34-45-45-115	1.4 V	16 GB x 2 pcs	Silver	XMP 3.0
B5HX100646030ER2G-BB006	64 GB	2R *8	6000 MT/s	CL30-38-38-76	1.35 V	32 GB x 2 pcs	Black	XMP 3.0 & E.X.P.O
B5HX100646030ER2G-BS006	64 GB	2R *8	6000 MT/s	CL30-38-38-76	1.35 V	32 GB x 2 pcs	Silver	XMP 3.0 & E.X.P.O
B5HX100646432FR2G-BB007	64 GB	2R *8	6400 MT/s	CL32-39-39-102	1.4 V	32 GB x 2 pcs	Black	XMP 3.0 & E.X.P.O
B5HX100646432FR2G-BS007	64 GB	2R *8	6400 MT/s	CL32-39-39-102	1.4 V	32 GB x 2 pcs	Silver	XMP 3.0 & E.X.P.O
B5HX100486432ER2G-BB010	48 GB	1R *8	6400 MT/s	CL32-39-39-102	1.35V	24 GB x 2 pcs	Black	XMP 3.0 & E.X.P.O
B5HX100486432ER2G-BS010	48 GB	1R *8	6400 MT/s	CL32-39-39-102	1.35V	24 GB x 2 pcs	Silver	XMP 3.0 & E.X.P.O
B5HX100486834ER2G-BB011	48 GB	1R *8	6800 MT/s	CL34-46-46-108	1.35 V	24 GB x 2 pcs	Black	XMP 3.0 & E.X.P.O
B5HX100486834ER2G-BS011	48 GB	1R *8	6800 MT/s	CL34-46-46-108	1.35V	24 GB x 2 pcs	Silver	XMP 3.0 & E.X.P.O
B5HX100487236ER2G-BB012	48 GB	1R *8	7200 MT/s	CL36-46-46-118	1.35 V	24 GB x 2 pcs	Black	XMP 3.0
B5HX100487236ER2G-BS012	48 GB	1R *8	7200 MT/s	CL36-46-46-115	1.35 V	24 GB x 2 pcs	Silver	XMP 3.0
B5HX100326032ER2G-BB013	32 GB	1R *8	6000 MT/s	CL32-38-38-76	1.35 V	16 GB x 2 pcs	Black	XMP 3.0 & E.X.P.O
B5HX100326032ER2G-BS013	32 GB	1R *8	6000 MT/s	CL32-38-38-76	1.35 V	16GB x 2 pcs	Silver	XMP 3.0 & E.X.P.O

1. Tested by BIWIN labs. Actual performance may vary due to systems, devices, or environment.
2. Maintenance and future updates are required throughout the product life cycle. Specifications are subject to change without notice.
3. The pictures are for illustration only. Actual products may vary due to product enhancements or changes.
4. Not all products are sold in all regions of the world.
5. As used for storage capacity, one megabyte (MB)= one million bytes, one gigabyte (GB) = one billion bytes, and one terabyte (TB) = one trillion bytes. Total accessible capacity varies depending on the operating environment. As used for buffer or cache, one megabyte (MB) = 1,048,576 bytes. As used for transfer rate or interface, megabyte per second (MB/s) = one million bytes per second, and gigabyte per second (GB/s) = one billion bytes per second.
6. Measured using the MobileMark™ 2012 benchmark with DIPM (Device Induced Power Management) enabled.
7. MTBF = Mean Time Between Failures based on internal testing using Telcordia stress testing standard.
8. For more details, please visit www.biwintech.com.

Global Headquarters:

BIWIN STORAGE TECHNOLOGY CO., LTD.
Building #4, South Zone #2, Zhongguan Honghualing Industrial Zone,
Nanshan District, Shenzhen, Guangdong, China
support@biwintech.com
www.biwintech.com

America Headquarters:

BIWIN TECHNOLOGY LLC
8725 NW 18th Terrece Suite 400, Miami, FL 33172, U.S.A
+1 (305) 456-3288

BIWIN SEMICONDUCTOR (HK) COMPANY LIMITED (Taipei Office)
2nd Floor, No. 158, Xinhua 2nd Road, Neihu District, Taipei City 114, Taiwan
+886 (2) 2795-282

